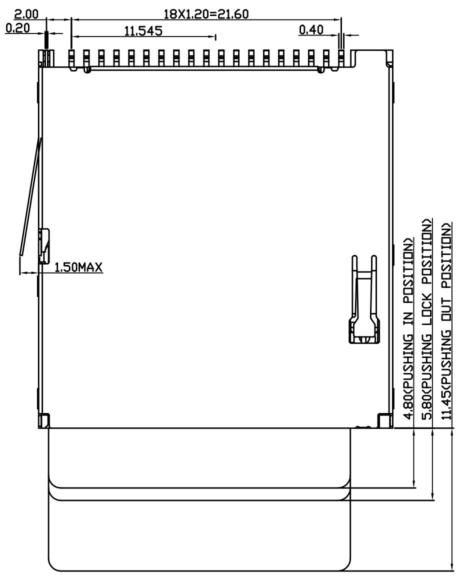
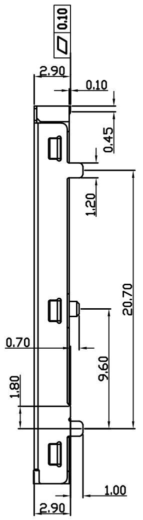
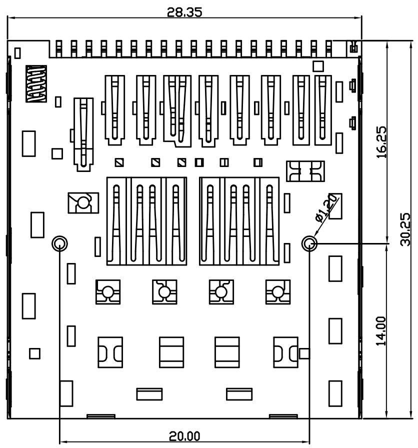
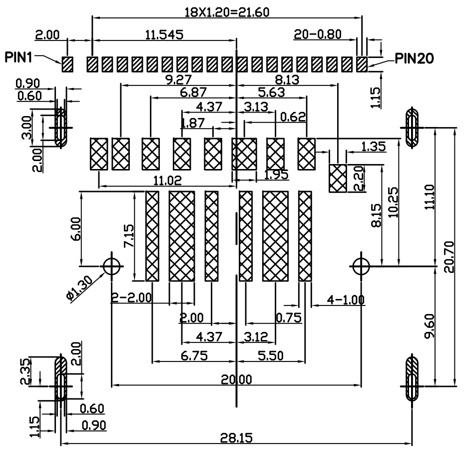
更改 REV	設變內容 MODIFICATION
A	ECXXXXX





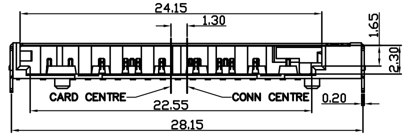




RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ±0.05)

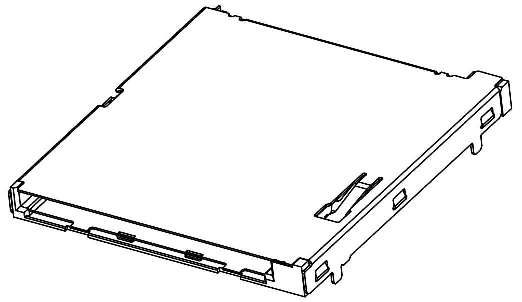
▨ PAD AREA

▩ NO TRACE,NO TEST POINT,
NO VIA HOLE.NO GROUND AREA



NOTES :

1. MATERIAL :
   - 1.1 HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
   - 1.2 SHELL:STAINLESS STEEL SUS304.
   - 1.3 CONTACT:COPPER ALLOY C5210.
2. FINISH :
   - 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
   - 2.2 SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u"MIN ON SOLDERTAIL AREA.
3. EIECTRICAL CHARACTERISTICS:
   - 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
   - 3.2 CURRENT RATING : 0.5 A.
   - 3.3 OPERATING TEMPERATURE: -25°C~+85°C.
   - 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
   - 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
   - 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.



WITHOUT CARD	CARD INSERTED:LOCK
C/D #12 ○–○╱ VSS1 #11 ○–○	C/D #12 ○–○–––○–○ VSS1 #11

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°

KINGCONN 皇海科技股份有限公司

名稱(TITLE) SD4.0 Push H2.90 CONN

單位(UNIT)	料號(PART NO.)	圖號(DWG NO.)
mm	7SD40-FA-0005	7SD40-FA-0005-A

審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)	比例 SCALE 1:1	張數 SHEET 1/3
			角法 PROJ.	更改 REV A

更改 REV	設變內容 MODIFICATION
A	ECXXXXX

Pin Define

Connector PinNo.	Specifications SD4.0 PinNo.	Specifications MMC PinNo.	SD Mode			UHS–II Mode			MMC		
			Name	Type	Description	Name	Type	Description	Name	Type	Description
P1			WP			WP					
P2	P8		DAT1	I/O/PP	Data Line[Bit 1]	RCLK–	I				
P3	P7	P7	DAT0	I/O/PP	Data Line[Bit 0]	RCLK+	I		DAT	I/O/PP	Data
P4	P17		—		Not Used(Connected to ground)	VSS5	S	Supply voltage ground			
P5	P6	P6	VSS2	S	Supply voltage ground	VSS2	S	Supply voltage ground	VSS	S	Supply voltage ground
P6	P16		—		Not Used	D1+	LVDS				
P7	P5	P5	CLK	I	Clock	—		Not Used	CLK	I	Clock
P8	P15		—		Not Used	D1–	LVDS				
P9	P4	P4	VDD	S	Supply voltage	VDD1	S	Supply voltage(3.3V)	VDD	S	Supply voltage
P10	P14		—		Not Used	VDD2	S	Supply voltage(1.8V)			
P11	P3	P3	VSS1	S	Supply voltage ground	VSS1	S	Supply voltage ground	VSS	S	Supply voltage ground
P12			CD			CD					
P13	P13		—		Not Used(Connected to ground)	VSS4	S	Supply voltage ground			
P14	P2	P2	CMD	PP	Command/Response	—		Not Used	CMD	I/O/PP/OD	Command/Reserved
P15	P12		—		Not Used	D0–	LVDS				
P16	P1	P1	CD/DAT3	I/O/PP	Card Detect/ Data Line[Bit 3]	—		Not Used	RSV	NC	Reserved for future use
P17	P11		—		Not Used	D0+	LVDS				
P18	P9		DAT2	I/O/PP	Data Line[Bit 2]	—					
P19	P10		—		Not Used(Connected to ground)	VSS3	S	Supply voltage ground			
P20			GND			GND			GND		
P21			GND			GND			GND		
P22			GND			GND			GND		
P23			GND			GND			GND		
P24			GND			GND			GND		

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5 °
.X± 0.30	.X°± 2 °
.XX± 0.20	.XX°± 1 °

KINGCONN 皇海科技股份有限公司

名 稱(TITLE) SD4.0 Push H2.90 CONN

單 位(UNIT) mm	料 號(PART NO.) 7SD40-FA-0005		圖 號(DWG NO.) 7SD40-FA-0005-A
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比例 SCALE 1:1
			張數 SHEET 2/3
			角法 PROJ.
			更改 REV A

更改 REV	設變內容 MODIFICATION
A	ECXXXXX

包裝作業規範

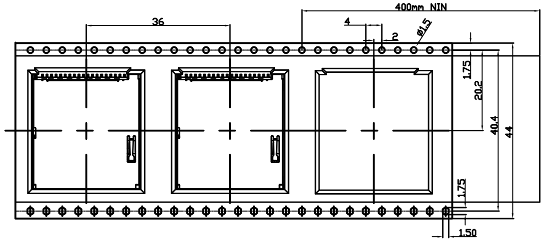
包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

一.

1) 將成品一一放入REEL包裝盤內,依同一方向放入 .

2) 包裝時,如圖所示 .

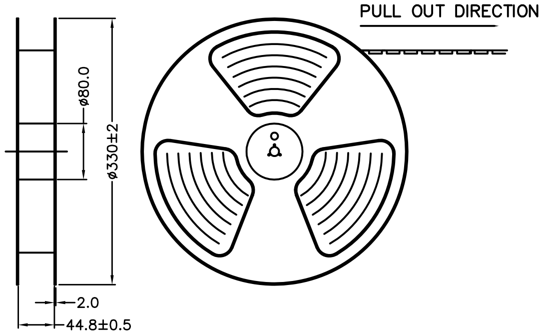
3) 一個REEL包裝盤放置300 個成品 .



二.

1)裝盤前先把前面空10pcs產品,然後再開始裝盤，尾端也需空10pcs產品,自粘帶加長200mm。

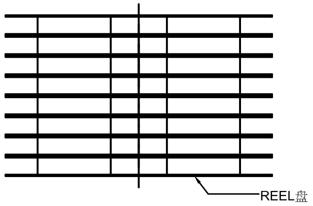
2)裝滿成品的REEL包裝盤如下圖所示。

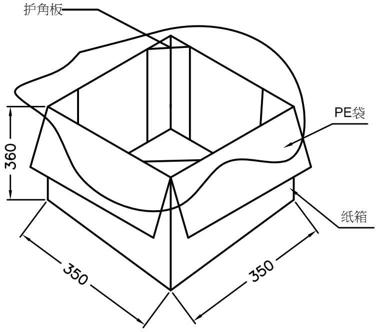


三.

1) 每箱裝 7 盤REEL包裝盤 .

2) 每箱放置 2100 PCS 的成品 .





四.

1) 用TAPE將紙箱封實 .

備 註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿 .

GENERIAL TOLERANCE		KINGCONN 皇海科技股份有限公司		
X.± 0.50	X.°± 5 °	名 稱(TITLE) SD4.0 Push H2.90 CONN		
.X± 0.30	.X°± 2 °			
.XX± 0.20	.XX°± 1 °			
單 位(UNIT) mm	料 號(PART NO.) 7SD40-FA-0005		圖 號(DWG NO.) 7SD40-FA-0005-A	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比例 SCALE 1:1	張數 SHEET 3/3
			角法 PROJ.	更改 REV A

RoHS